

Features

- Split Gate Trench MOSFET Technology
- High Density Cell Design for Low $R_{DS(on)}$
- Halogen Free "Green" Device^(Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Moisture Sensitivity Level 1

Maximum Ratings

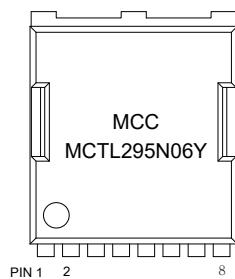
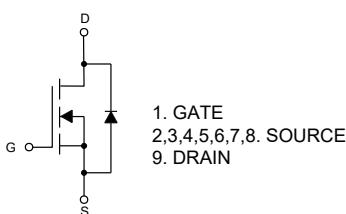
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 30°C/W Junction to Ambient^(Note2)
- Thermal Resistance: 0.4°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_c=25^\circ\text{C}$	I_D	295	A
		187	A
Pulsed Drain Current ^(Note3)	I_{DM}	1200	A
Total Power Dissipation ^(Note4)	P_D	313	W
Single Pulsed Avalanche Energy ^(Note5)	E_{AS}	1690	mJ

Note:

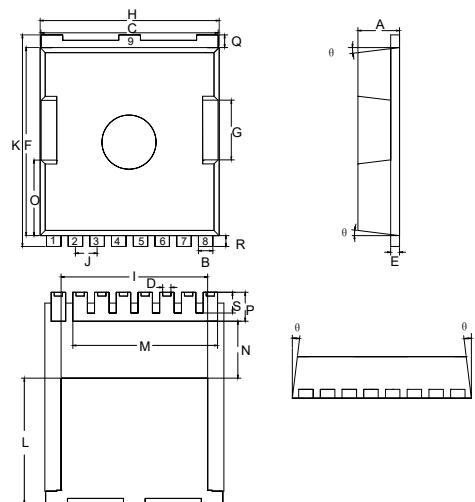
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA} \leq 10$ s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $L=5\text{mH}$

Internal Structure and Marking Code



N-CHANNEL MOSFET

TOLL-8L



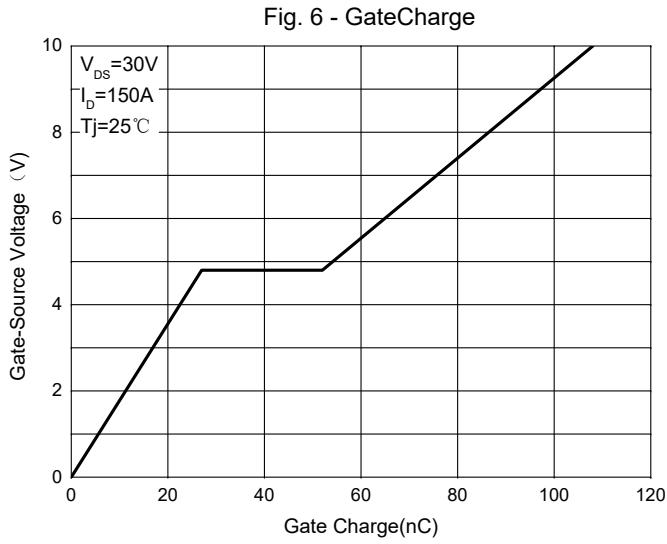
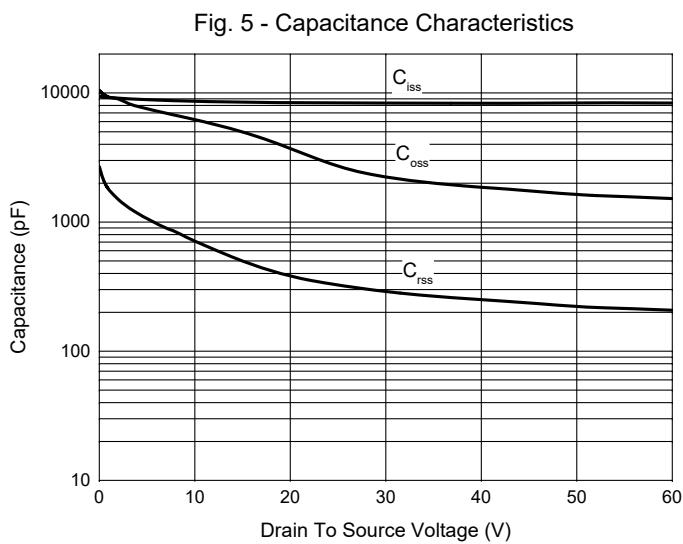
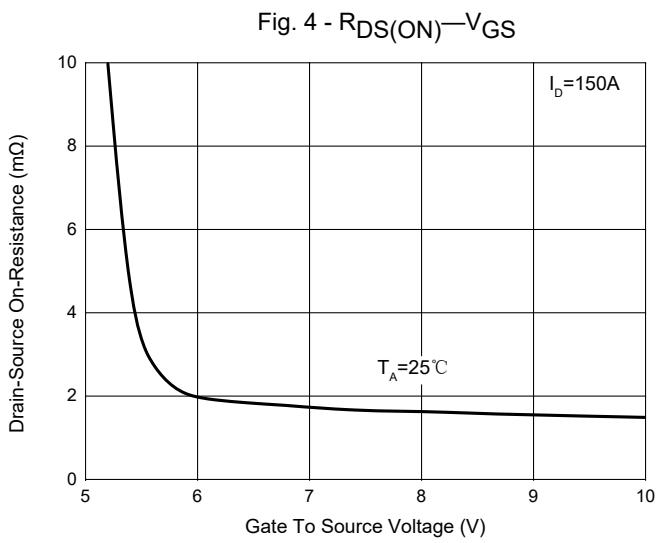
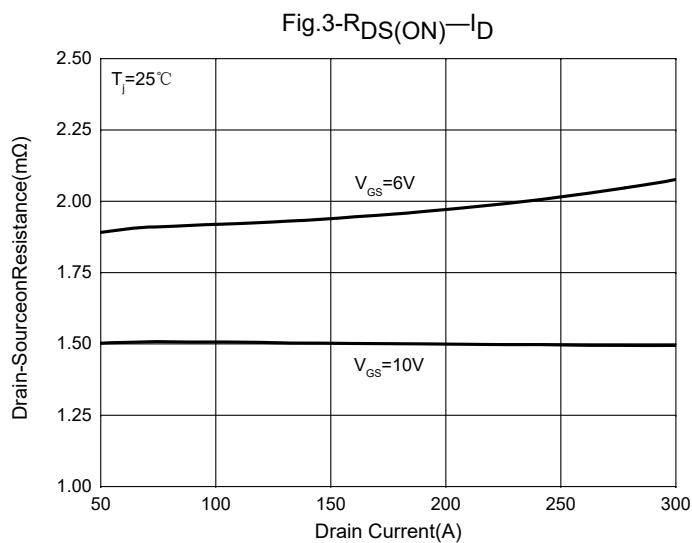
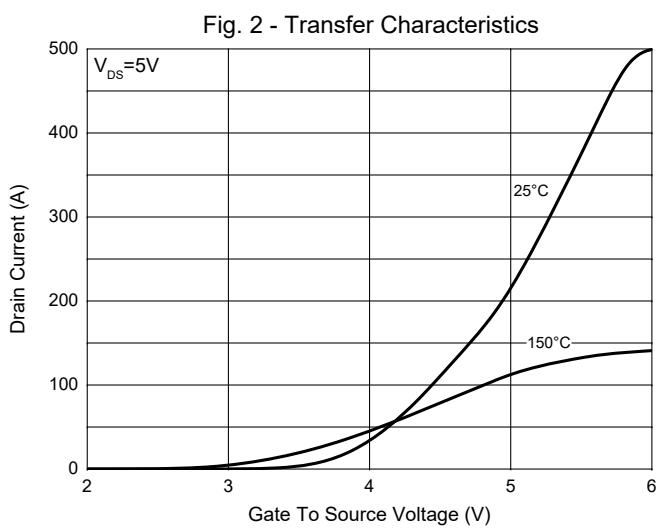
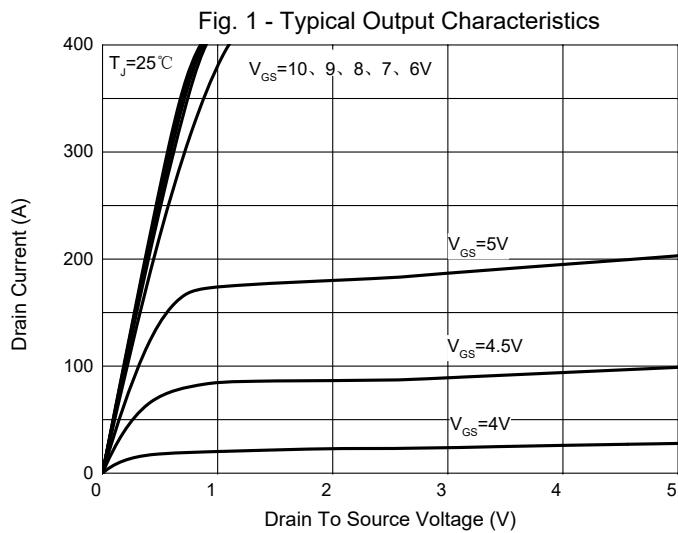
DIMENSIONS

DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.087	0.094	2.20	2.40	
B	0.028	0.035	0.70	0.90	
C	0.382	0.390	9.70	9.90	
D	0.017	0.020	0.42	0.50	
E	0.016	0.024	0.40	0.60	
F	0.405	0.417	10.28	10.58	
G	0.122	0.138	3.10	3.50	
H	0.382	0.398	9.70	10.10	
I	0.311	0.327	7.90	8.30	
J	0.047		1.20		BSC
K	0.452	0.468	11.48	11.88	
L	0.266	0.281	6.75	7.15	
M	0.315		8.00		
N	0.118	0.130	3.00	3.30	
O	0.157	0.172	3.98	4.38	
P	0.055	0.071	1.40	1.80	
Q	0.024	0.031	0.60	0.80	
R	0.020	0.028	0.50	0.70	
S	0.039	0.051	1.00	1.30	
θ	4°	10°	4°	10°	

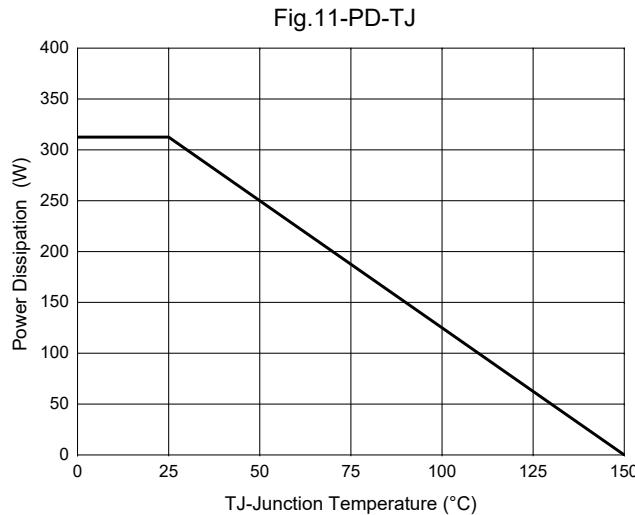
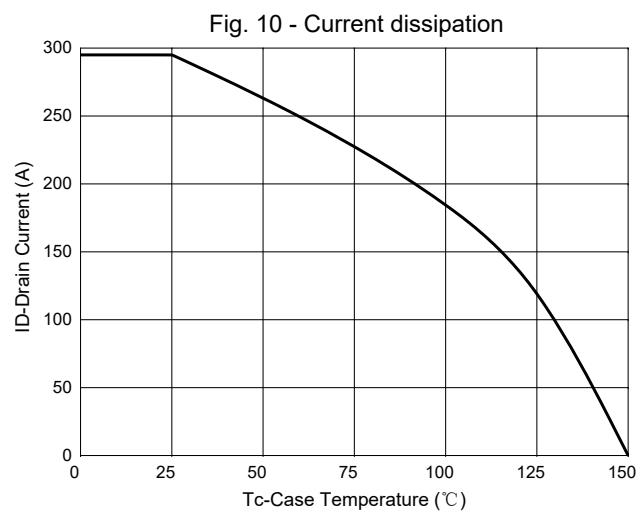
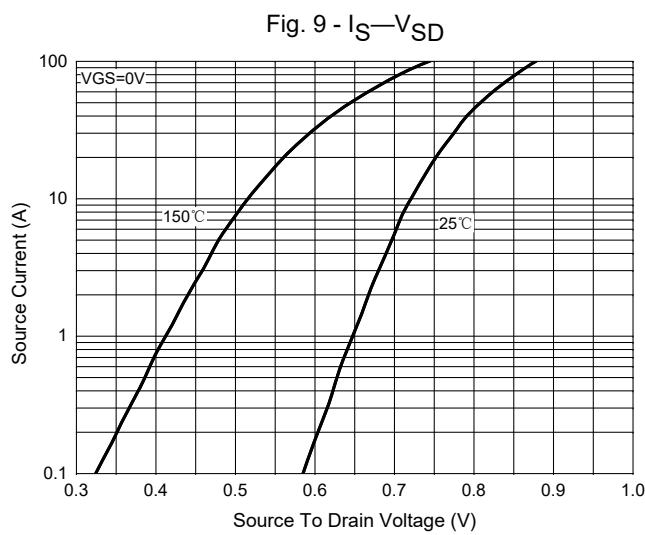
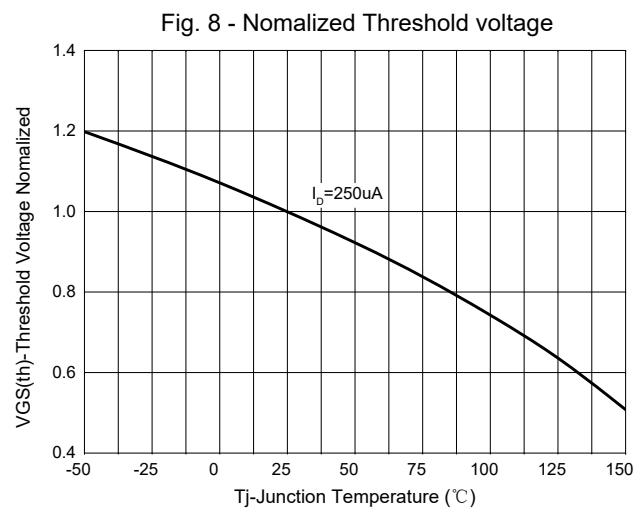
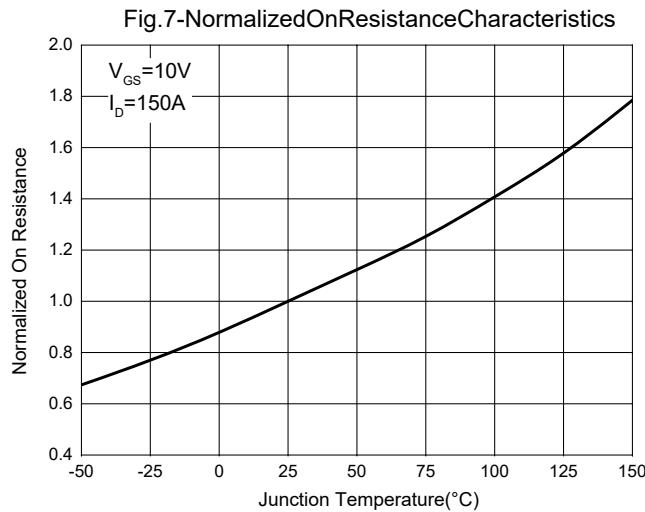
Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$			1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.5	2.5	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		1.5	2	mΩ
		$V_{GS}=6V, I_D=20A$		1.85	2.7	
Gate Resistance	R_g	F=1 MHz, Open drain		1.1		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				295	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=150A$			1.2	V
Reverse Recovery Time	t_{rr}	$I_S=150A, di/dt=100A/\mu s$		80		ns
Reverse Recovery Charge	Q_{rr}			208		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V, f=1MHz$		8350		pF
Output Capacitance	C_{oss}			2200		
Reverse Transfer Capacitance	C_{rss}			300		
Total Gate Charge	Q_g	$V_{DS}=30V, V_{GS}=10V, I_D=150A$		108		nC
Gate-Source Charge	Q_{gs}			27		
Gate-Drain Charge	Q_{gd}			25		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=30V, V_{GS}=10V, R_G=2.2\Omega, I_{DS}=150A$		33		ns
Turn-On Rise Time	t_r			69		
Turn-Off Delay Time	$t_{d(off)}$			172		
Turn-Off Fall Time	t_f			105		

Curve Characteristics



Curve Characteristics



Curve Characteristics

Fig. 12 - Safe Operation Area

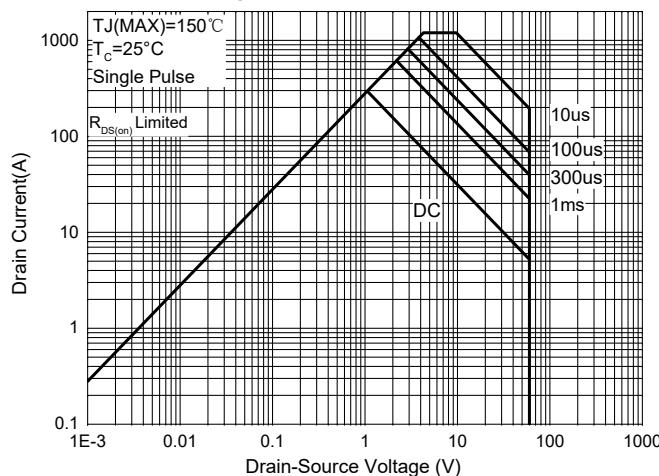
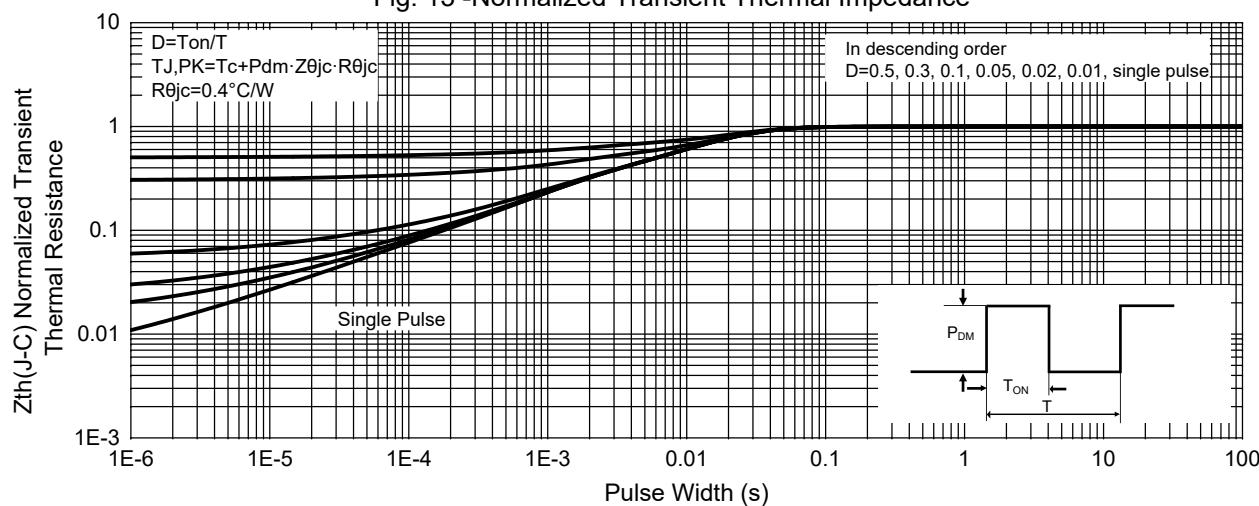


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 2Kpcs/Reel

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